

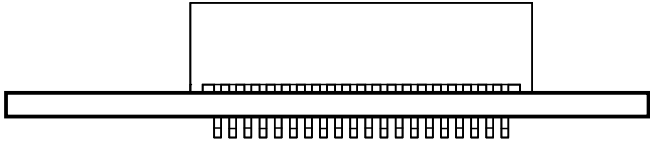
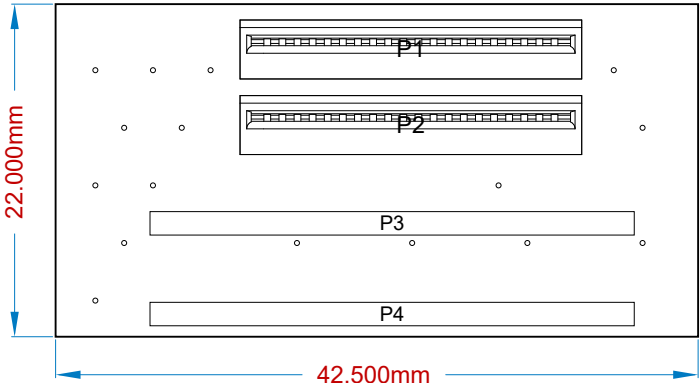
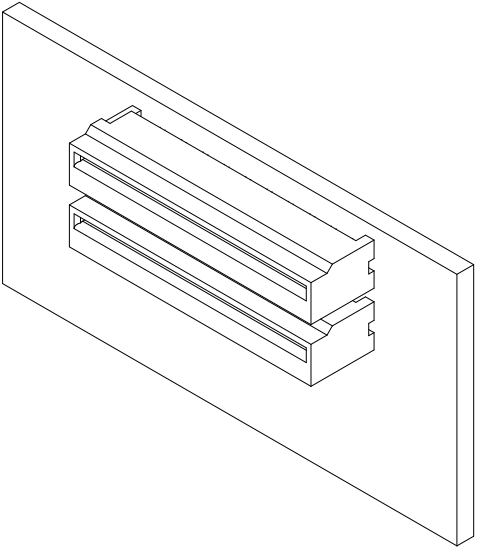
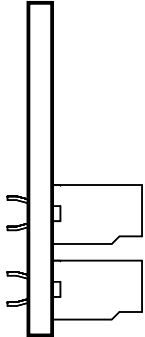
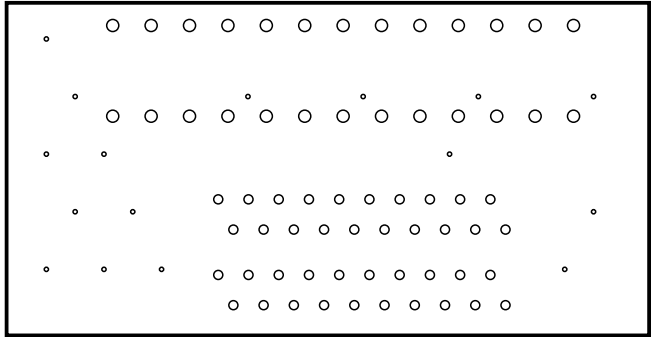
Quantity	Designator	Description	Manufacturer	Manufacturer Part Number	Supplier 1	Supplier Part Number 1
2	P1, P2	20PIN FPC HLW20S-2C7LF	Amphenol FCI	HLW20S-2C7LF	Digi-Key	609-1835-ND
2	P3, P4	2.54mm Header 13-Pin				

A

B

C

D



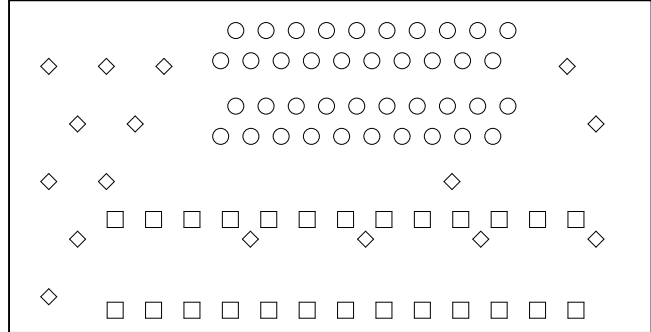
A

B

C

D

Drill Drawing View (Scale 2:1)



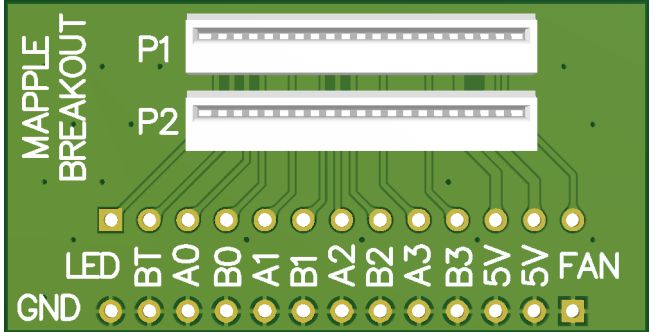
Drill Table

Symbol	Count	Hole Size	Plated	Hole Tolerance
◇	16	0.381mm	Plated	None
○	40	0.700mm	Plated	None
□	26	0.900mm	Plated	None
82 Total				

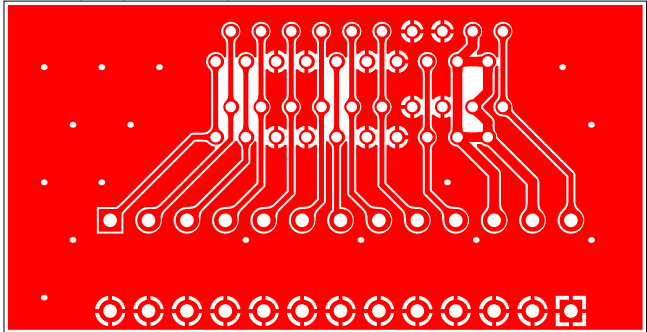
Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
	Surface Material	0.025mm	SM-001	Solder Mask	GTS
CF-004	Top Layer	0.035mm		Signal	GTL
Core		1.499mm	Core-043	Dielectric	
CF-004	Bottom Layer	0.035mm		Signal	GBL
	Bottom Solder	0.025mm	SM-001	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
Total thickness: 1.619mm					

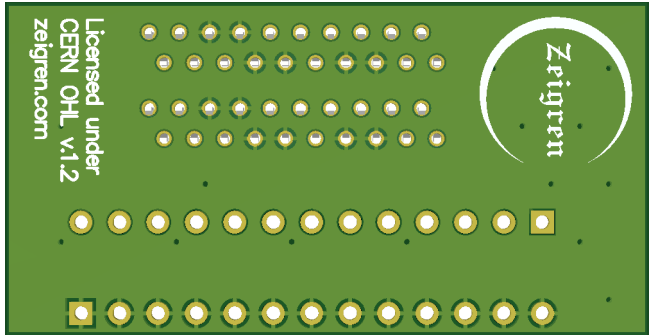
Top



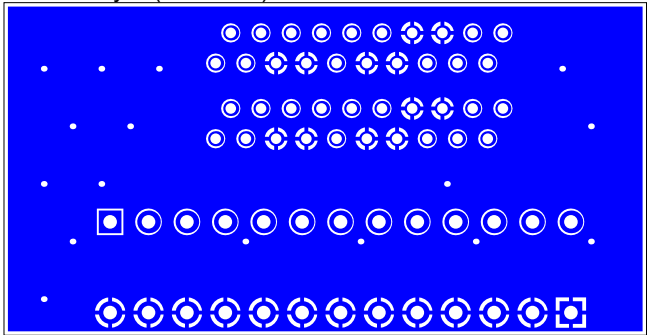
Top Layer (Scale 2:1)



Bottom



Bottom Layer (Scale 2:1)



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Maple Breakout Board		
Drawn By: Zeigren		
Revision:	Size: B	Scale: 2:1
Date: 10/26/2019	Time: 10:11 PM	Sheet: 2 of 2
File: MapleBreakout.PCBDwf		

